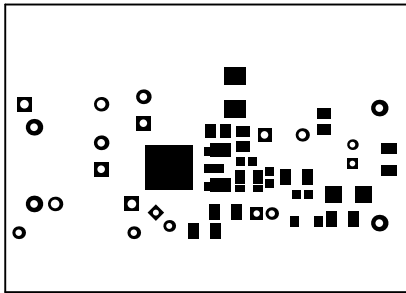
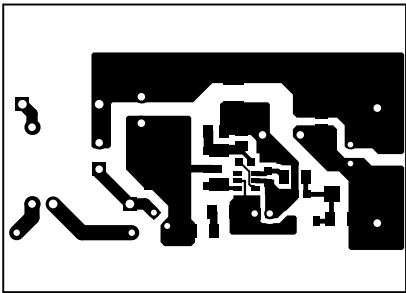


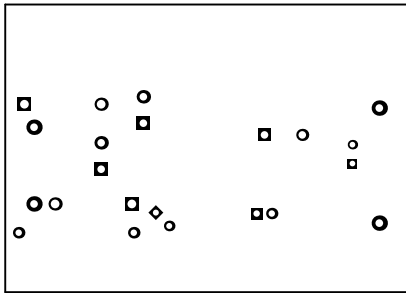
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/20/2017 9:53:16 AM	TEXAS INSTRUMENTS	



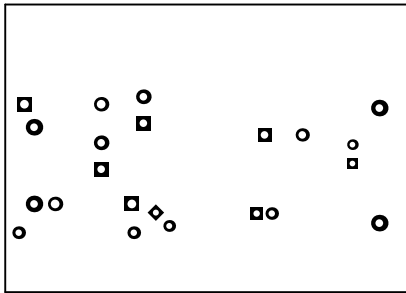
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/20/2017 9:53:18 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/20/2017 9:53:19 AM	TEXAS INSTRUMENTS	



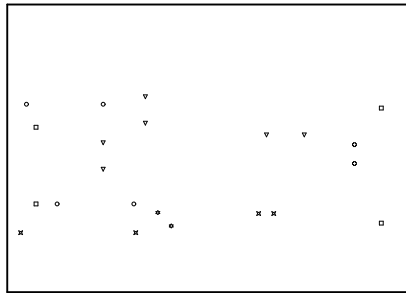
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/20/2017 9:53:21 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/20/2017 9:53:23 AM	TEXAS INSTRUMENTS	



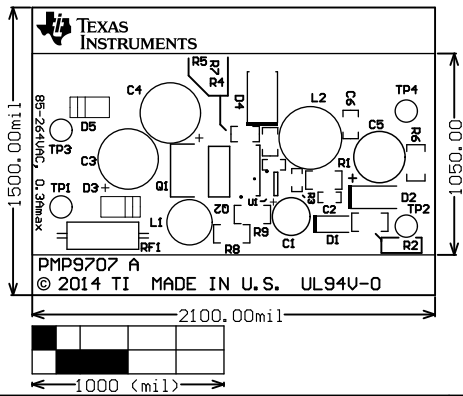
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/20/2017 9:53:24 AM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type
⊗	2	29.53mil (0.750mm)	PTH	Round
☆	2	31.00mil (0.787mm)	PTH	Round
✱	4	33.47mil (0.850mm)	PTH	Round
□	4	40.00mil (1.016mm)	PTH	Round
○	4	45.28mil (1.150mm)	PTH	Round
▽	6	39.37mil (1.000mm)	PTH	Round
	22 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/20/2017 9:53:26 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9707	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MapBoardDimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/20/2017 9:53:28 AM	TEXAS INSTRUMENTS	

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